



RE931

- Epoxy fibre-glass 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for 7 different SSOP's
- Pitch: 0.65 mm & 0.635 mm
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual moduls from the board
- Size 61.40 x 81.70 mm

Module-No.	Pitch	mil	Pin	Size (mm)
RE931-01	0.650 mm	25.6	14	5.300 (208 mil)
RE931-02	0.650 mm	25.6	16	5.300 (208 mil)
RE931-03	0.650 mm	25.6	20	5.300 (208 mil)
RE931-04	0.650 mm	25.6	24	5.300 (208 mil)
RE931-05	0.650 mm	25.6	28	5.300 (208 mil)
RE931-06	0.635 mm	25.0	48	7.500 (295 mil)
RE931-07	0.635 mm	25.0	56	7.500 (295 mil)